

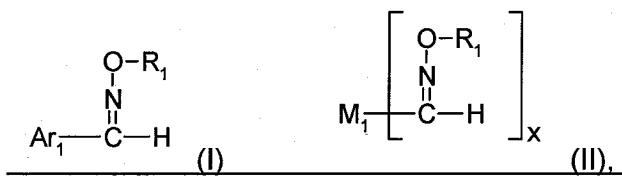
In the Claims

1-4 (cancelled)

5. (currently amended) Photosensitive composition according to claim [[1]], wherein component (B) is a compound of formula I or II, wherein Alkaline developable, photosensitive composition comprising

(A) at least one alkaline soluble binder resin, prepolymer or monomer component;

(B) at least one compound of formula I or II



wherein

R₁ is C₂-C₄ alkanoyl;

Ar₁ is phenyl or naphthyl, each of which is substituted by halogen, C₁-C₆alkyl, NR₅R₆ or OR₃, wherein the substituents OR₃, optionally form 5- or 6-membered rings *via* the radicals R₃ with further substituents on the phenyl or naphthyl ring; or provided that R₁ is acetyl, Ar₁ is 2-furyl, 2-pyrrolyl, 2-thienyl, 3-indolyl;



M_1 is ;

x is 2;

R₃ is C₁-C₂₀alkyl; or R₃ is C₂-C₁₂alkyl which is substituted by OH, -O(CO)-C₁-C₄alkyl, -N(C₁-

$\text{C}_4\text{alkyl})_2$, $-\text{N}(\text{CH}_2\text{CH}_2\text{OH})_2$, $-\text{N}[\text{CH}_2\text{CH}_2\text{O}-(\text{CO})-\text{C}_1\text{-C}_4\text{alkyl}$ or morpholinyl; or R_3 is $\text{C}_2\text{-C}_{12}\text{alkyl}$ which is interrupted by one or more $-\text{O}-$; or R_3 is $-(\text{CH}_2\text{CH}_2\text{O})_{n+1}\text{H}$ or $-(\text{CH}_2\text{CH}_2\text{O})_n(\text{CO})-\text{C}_1\text{-C}_4\text{alkyl}$;

n is 1 to 3; and

R₅ and **R₆** are C₁-C₄alkyl

(C) a photopolymerizable compound

and which composition additionally comprises an epoxy compound which contains at least two epoxy groups in the molecule.

6-7.(cancelled)

8. **(currently amended)** Photosensitive composition according to claim [[4]] 5, which additionally to the components (A), (B) and (C) comprises at least one photosensitizer compound (D).
9. **(previously presented)** Photosensitive composition according to claim 8, comprising 100 parts by weight of component (A), 0.015 to 120 parts by weight of component (B), 5 to 500 parts by weight of component (C) and 0.015 to 120 parts by weight of component (D).
10. **(currently amended)** Photosensitive composition according to claim [[4]] 5, comprising further additives (E), which are selected from the group consisting of thermal polymerization inhibitors, inorganic fillers, colourants, epoxy curing agents, amines, chain transfer agents, thermal radical initiators, photoreducible dyes, optical brighteners, thickeners, antifoaming agents and leveling agents, in particular inorganic fillers.
11. **(cancelled)**
12. **(currently amended)** Solder resist comprising a composition according to claim [[4]] 5.
13. **(currently amended)** Color filter resist comprising a composition according to claim [[4]] 5.
14. **(currently amended)** Process for the photopolymerization of compounds containing ethylenically unsaturated double bonds, which comprises irradiating a composition according to claim [[4]] 5 with electromagnetic radiation in the range from 150 to 600 nm.
15. **(currently amended)** Coated substrate which is coated on at least one surface with a composition according to claim [[4]] 5.
- 16-17. **(cancelled)**

18. (currently amended) Process for forming images, wherein

(1) the components of a composition according to claim [[1]] are mixed,

(2) the resulting composition is applied to the substrate,

(3) the solvent, if present, is evaporated, at elevated temperature,

(4) the coated substrate according to claim 15 is patternwise exposed to irradiation, and then

(5) the irradiated sample is developed with aqueous alkaline solution, thereby removing the to remove

uncured areas followed by thermal curing. — and

(6) the sample is thermally cured.

19. (currently amended) Photosensitive composition according to claim [[4]] 5, wherein compound (A) is an oligomeric or polymeric compound.

20. (currently amended) Photosensitive composition according to claim [[4]] 5, wherein the photopolymerizable compound (C) is a liquid.